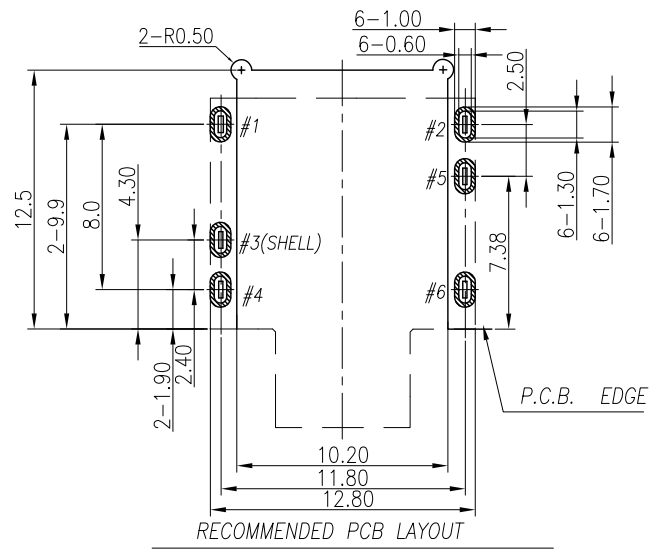
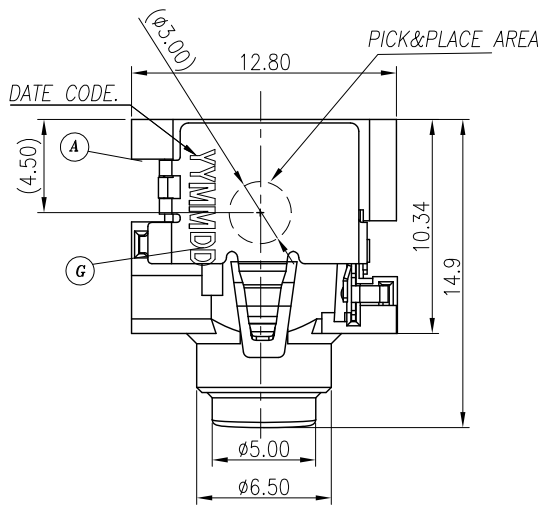
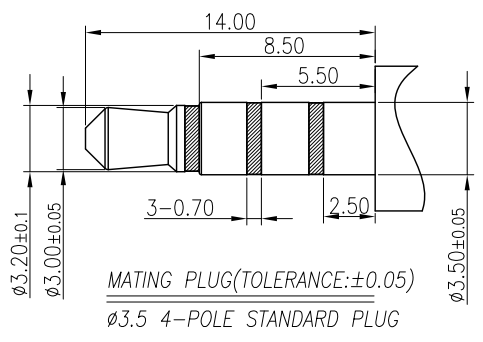
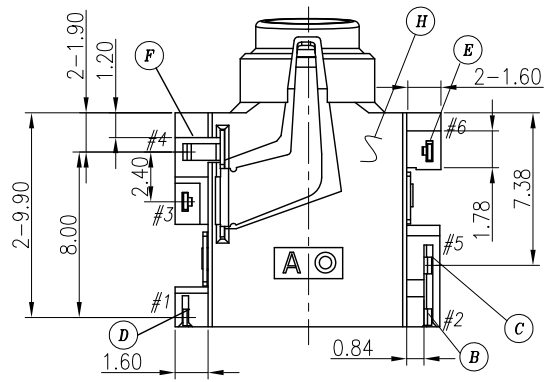
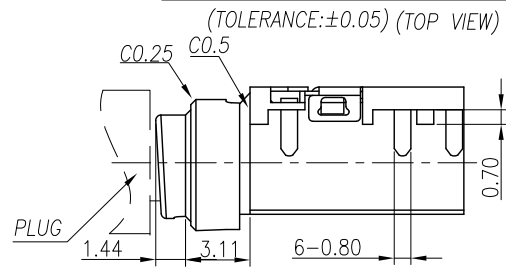
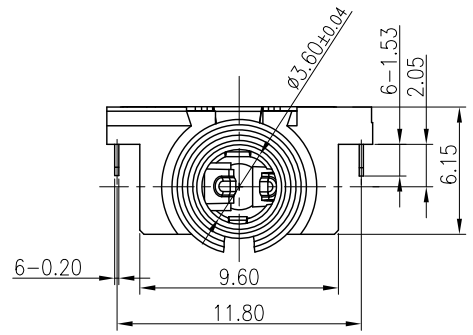
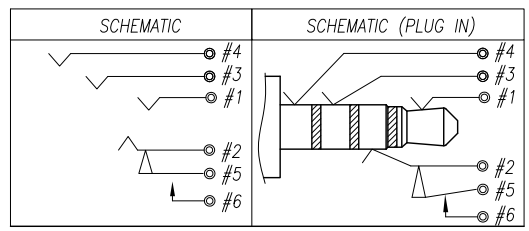


1	7	8	
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T121108-11A	Aaron	2013.05.08



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC .
 - CONTACT RESISTANCE :50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
 - LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE :(INITIAL : 0.4 - 3.0Kg.)(LIFE TEST: 0.3 - 3.0Kg.)
 - WITHDRAWAL FORCE :(INITIAL : 0.4 - 3.0Kg.)(LIFE TEST: 0.3 - 3.0Kg.)
 - PACKAGING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ☉
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: ☉



H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC	BLACK
G	SHIELDING	1	COPPER ALLOY, 0.2T	NICKEL 50u" Min
F	EARTH	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA MATTE SN 120u" ON SOLDER AREA, ALL OVER 60u" NICKEL PLATING.
E	BREAK TERMINAL	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA, ALL OVER 60u" NICKEL PLATING.
D	TIP	1	COPPER ALLOY, 0.2T	
C	TRANSFER	1	COPPER ALLOY, 0.2T	
B	RING SPRING	1	COPPER ALLOY, 0.2T	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE		
X : ±0.5	X : ±2°	DWN	Aaron	3.5φ PHONE JACK
X.X : ±0.3	X.X : ±1°	CHKD	Bruce	PART NO.2SJ3086-007111F
X.XX : ±0.2		APVD	Lussen	SCALE: 4:1 UNIT: mm
				SIZE: A3 SHEET: 1 OF 1
		REV:A		
CUSTOMER COPY				